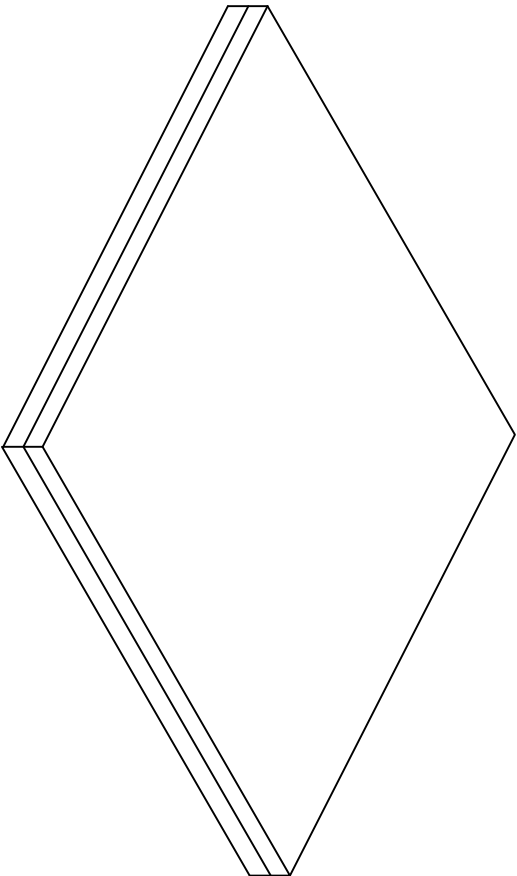


REVISION HISTORY						
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DRAWING FILE NAME	GERBER FILE NAME	DATE
00	N/A	INITIAL RELEASE	ETHONG	N/A	N/A	02/28/05



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC. #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC. #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 441.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 21 X 21.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.65mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Amkor Technology, Inc. Chandler, Arizona, USA Amkor Semiconductor, Inc., Seoul, Korea Amkor Technology Philippines, Inc., Cebu, Philippines	
DECIMAL X.X ±0.1	ANGULAR ±1°	DESIGNED	DATE		
X.XX ±0.05		ETHONG	02/02/05		
X.XXX ±0.030		SMKANG	02/02/05		
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		PRODUCT MANAGER	02/02/05		
MATERIAL	N/A	VP/ERE	02/28/05	SIZE	SD NUMBER
FINISH	N/A	RELEASED	02/28/05	A3	N/A
DO NOT SCALE DRAWING		SMSEO	02/28/05	STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.
				N/A	N/A
				SCALE	1:6
				SHEET	1 OF 3